

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SO TANAKA	07/21/2015
SHUNSUKE YAMADA	07/21/2015
TAKU HORII	07/21/2015
AKIRA MATSUSHIMA	07/22/2015
RYOSUKE KUBOTA	07/24/2015
KYOKO OKITA	07/22/2015
TAKAYUKI NISHIURA	08/01/2015
RECEIVING PARTY DATA	
Name:	SUMITOMO ELECTRIC INDUSTRIES, LTD.
Street Address:	5-33, KITAHAMA 4-CHOME, CHUO-KU
City:	OSAKA-SHI, OSAKA
State/Country:	JAPAN
Postal Code:	541-0041
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14786063
CORRESPONDENCE DATA	
Fax Number:	(202)344-8300
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-344-4000
Email:	jberryman@venable.com, ptomail@venable.com
Correspondent Name:	MICHAEL A. SARTORI, PH.D.
Address Line 1:	VENABLE LLP, P.O. BOX 34385
Address Line 4:	WASHINGTON, D.C. 20043-9998
ATTORNEY DOCKET NUMBER:	92396-390307
NAME OF SUBMITTER:	MICHAEL A. SARTORI, PH.D.
SIGNATURE:	/MICHAEL A. SARTORI, PH.D./
DATE SIGNED:	10/21/2015

Total Attachments: 2

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ATTORNEY DOCKET NO.

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

Application No. _____ Filed _____

Insert Name(s)
of Inventor(s)

WHEREAS, So TANAKA, Shunsuke YAMADA, Taku HORII,
Akira MATSUSHIMA, Ryosuke KUBOTA, Kyoko OKITA,
and Takayuki NISHIURA

Insert Title
of Invention

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in
Silicon Carbide Substrate, Silicon Carbide Semiconductor Device, and
Methods for Manufacturing Silicon Carbide Substrate and Silicon
Carbide Semiconductor Device
for which an application for Letters Patent of the United States of America has been executed by the undersigned (except in the case of a provisional application).

Insert Date of
Signing of
Application

on July 21, July 22, July 24 and August 1, 2015 ; and

Insert Name
of Assignee

WHEREAS, Sumitomo Electric Industries, Ltd.

Insert Address
of Assignee

of 5-33, Kitahama 4-chome, Chuo-ku, Osaka-shi, Osaka 541-0041 Japan

CHECK BOX
IF APPROPRIATE

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and in any and all foreign countries.

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries:

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

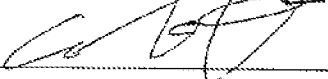
The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) the request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional, conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Venable LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

(1) Date July 21, 2015 , Name of Inventor 
So TANAKA

(2) Date July 21, 2015 , Name of Inventor Shunsuke YAMADA
Shunsuke YAMADA

(3) Date July 21, 2015 , Name of Inventor Taku HORII
Taku HORII

(4) Date July 22, 2015 , Name of Inventor Akira Matsushima
Akira MATSUSHIMA

(5) Date July 24, 2015 , Name of Inventor Ryosuke Kubota
Ryosuke KUBOTA

(6) Date July 22, 2015 , Name of Inventor Kyoko OKITA
Kyoko OKITA

(7) Date Aug. 01, 2015 , Name of Inventor Takayuki Nishiura
Takayuki NISHIURA